U-MAP Co., Ltd.
Ultimate Material and Processing

ThermaInite®

Reference Sample

High Thermal Conductivity Thermal Interface Sheet

Industry-leading thermal conductivity and flexibility
Optimized filler design achieves both properties

Items	Unit	Value
Thickness	mm	0.5, 1.0
Thermal Conductivity	W/m·K	10
Hardness (Shore OO)	°	96
Dielectric Strength	kV/mm	10.7*
Dielectric Constant (1 MHz)	–	8.9
Dielectric Loss (1 MHz)	–	3.1×10^{-2}

*Measured at 0.5 mm thickness

Features

High Thermal Conductivity
10 W/m·K

Soft & Flexible
Gap absorption

Resilience
Shape recovery / High reliability

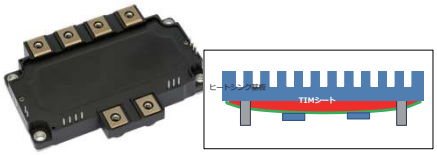
Oil-Free

Benefits

1. Maximizes output performance through improved heat dissipation
2. Absorbs part-to-part height variations
3. High conformability reduces thermal resistance
4. Improves assembly efficiency and reduces cost
5. Follows deformation and external vibration caused by heat
6. Maintains low thermal resistance with high reliability
7. Preserves the performance of mounted components

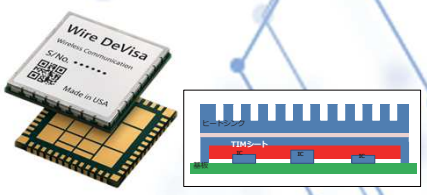
Applications

Power Modules



Motor Drive Units

Communication Module ICs



CPU